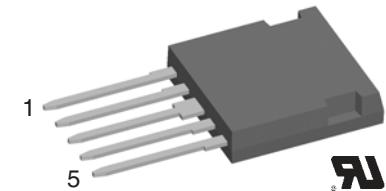
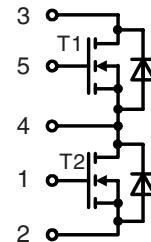


## Trench Power MOSFET

Phaseleg Topology  
in ISOPLUS i4-PAC™

**I<sub>D25</sub>** = 150 A  
**V<sub>DSS</sub>** = 75 V  
**R<sub>DS(on) typ</sub>** = 3.2 mΩ



### MOSFET T1/T2

Symbol	Conditions	Maximum Ratings		
V <sub>DSS</sub>	T <sub>VJ</sub> = 25°C to T <sub>VJmax</sub>	75		V
V <sub>GS</sub>		±20		V
I <sub>D25</sub>	T <sub>C</sub> = 25°C	150		A
I <sub>D90</sub>	T <sub>C</sub> = 90°C	120		A
I <sub>F25</sub>	(body diode) T <sub>C</sub> = 25°C	150		A
I <sub>F90</sub>	(body diode) T <sub>C</sub> = 90°C	100		A

Symbol	Conditions	Characteristic Values		
		(T <sub>VJ</sub> = 25°C, unless otherwise specified)	min.	typ.
R <sub>DSon</sub>	V <sub>GS</sub> = 10 V; I <sub>D</sub> = I <sub>D90</sub> ; on chip level		3.2	4.2 mΩ
V <sub>Gsth</sub>	V <sub>DS</sub> = 20 V; I <sub>D</sub> = 1 mA	2		4 V
I <sub>DSS</sub>	V <sub>DS</sub> = 75 V; V <sub>GS</sub> = 0 V; T <sub>VJ</sub> = 25°C T <sub>VJ</sub> = 125°C		0.1	10 μA mA
I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V; V <sub>DS</sub> = 0 V		200	nA
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 60 V; I <sub>D</sub> = 50 A	225		nC
t <sub>d(on)</sub> t <sub>r</sub>		30		nC
t <sub>d(off)</sub> t <sub>f</sub>		85		nC
E <sub>on</sub> E <sub>off</sub> E <sub>rec(off)</sub>	Inductive load, T <sub>VJ</sub> = 125°C V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 30 V I <sub>D</sub> = 120 A; R <sub>G</sub> = 10 Ω	75		ns
		100		ns
		400		ns
		90		ns
		0.31		mJ
		0.5		mJ
		0.05		mJ
V <sub>F</sub>	(body diode) I <sub>F</sub> = 75 A; V <sub>GS</sub> = 0 V	1.1	1.5	V
t <sub>rr</sub>	(body diode) I <sub>F</sub> = 20 A; -di/dt = 100 A/μs; V <sub>DS</sub> = 30 V	90		ns
R <sub>thJC</sub> R <sub>thJH</sub>	with heat transfer paste	1.0	0.6	K/W K/W

### Features

- trench MOSFET
  - very low on state resistance R<sub>DSon</sub>
  - fast switching
- ISOPLUS i4-PAC™ package
  - isolated back surface
  - low coupling capacity between pins and heatsink
  - enlarged creepage towards heatsink
  - application friendly pinout
  - low inductive current path
  - high reliability
  - industry standard outline
  - UL registered E 72873

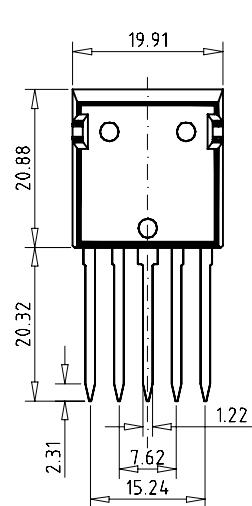
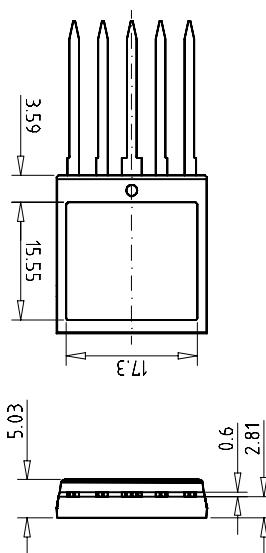
### Applications

- automotive
  - AC drives - starter generator for 42V etc.
  - choppers - replacing series resistors for DC drives, heating etc.
  - DC-DC converters - between 12V and 42V system etc.
  - electronic switches -replacing relays and fuses
- power supplies
  - DC-DC converters
  - solar inverters
- battery supplied systems
  - choppers or inverters for drives in hand held tools
  - battery chargers

**Component**

Symbol	Conditions	Maximum Ratings	
$I_{RMS}$	per pin	75	A
$T_{VJ}$		-55...+175	°C
$T_{stg}$		-55...+125	°C
$V_{ISOL}$	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$	2500	V~
$F_c$	mounting force with clip	20...120	N

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$R_{pin-chip}$	$R_{pin-P2} > R_{DS(on)} + R_{pin-chip}$	1.6		mΩ
$C_p$	coupling capacity between shorted pins and mounting tab in the case	40		pF
$d_s, d_A$	pin - pin	1.7		mm
$d_s, d_A$	pin - backside metal	5.5		mm
<b>Weight</b>		9		g

**Dimensions in mm (1 mm = 0.0394")**

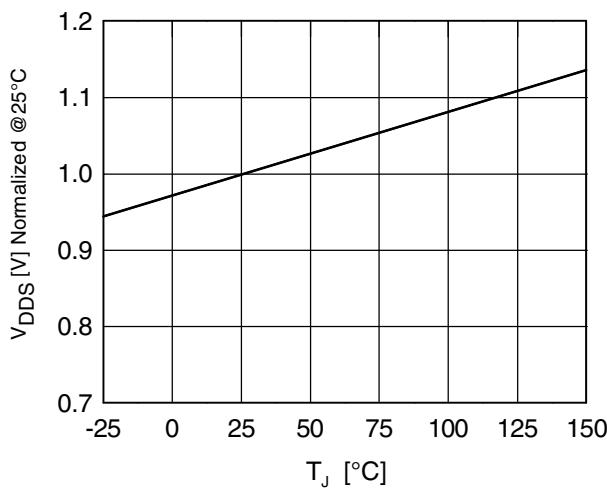


Fig. 1 Drain source breakdown voltage  $V_{DSS}$  vs. junction temperature  $T_{VJ}$

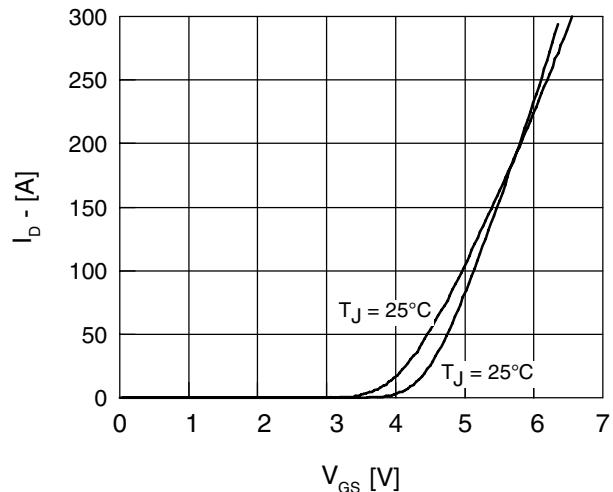


Fig. 2 Typical transfer characteristic

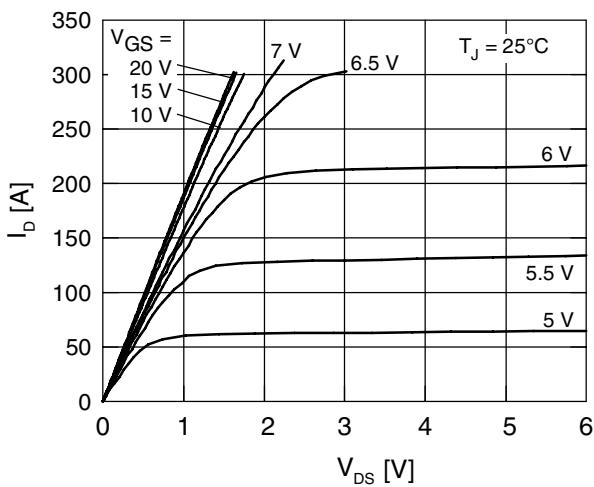


Fig. 3 Typical output characteristic

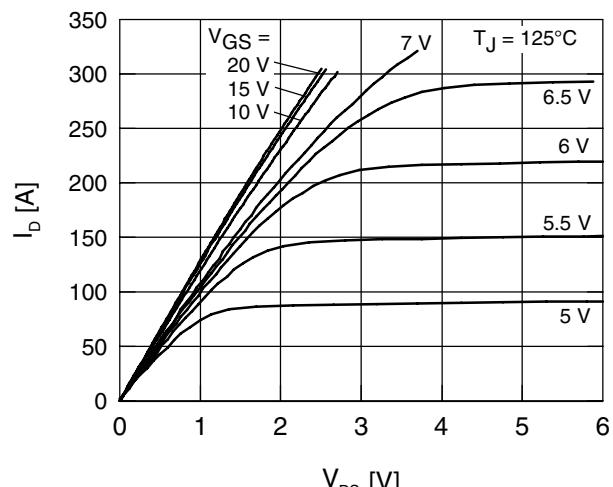


Fig. 4 Typical output characteristic

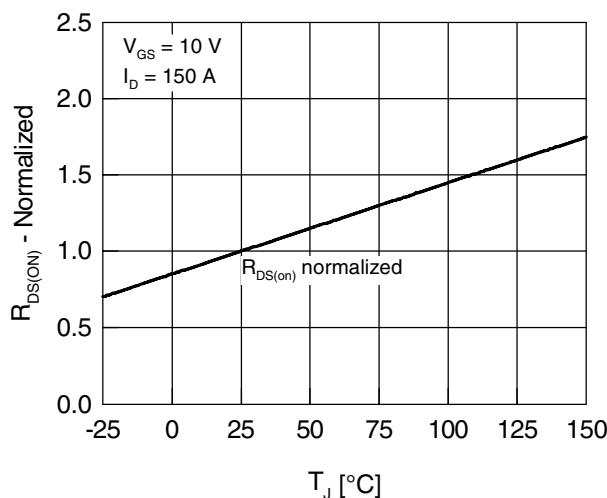


Fig. 5 Drain source on-state resistance  $R_{DS(on)}$  vs. junction temperature  $T_{VJ}$

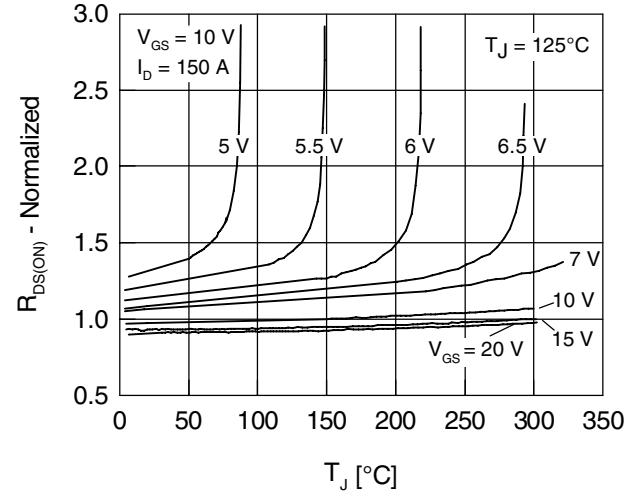


Fig. 6 Drain source on-state resistance  $R_{DS(on)}$  versus  $I_D$

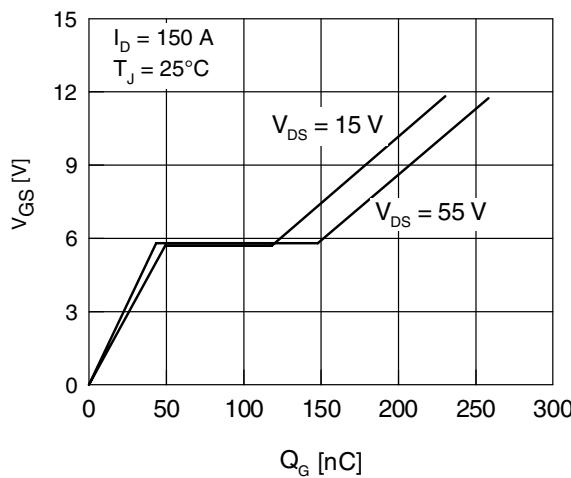


Fig. 7 Gate charge characteristic

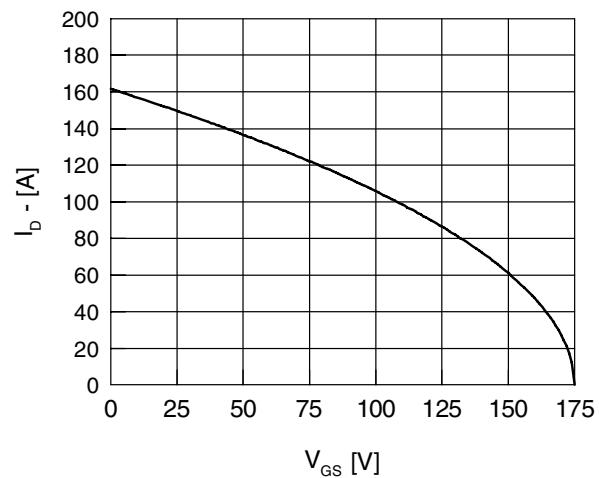


Fig. 8 Drain current  $I_D$  vs. case temperature  $T_c$

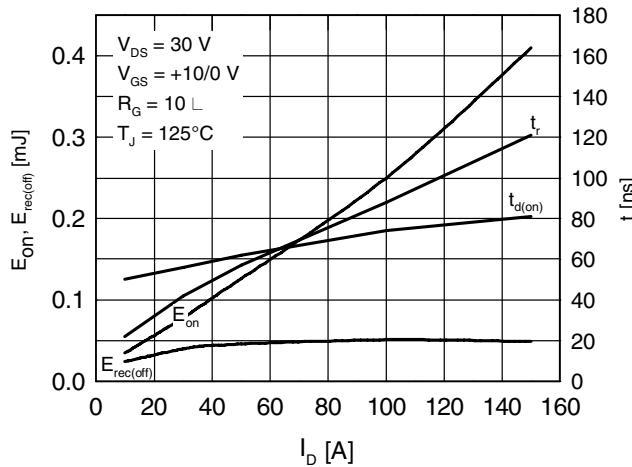


Fig. 9 Typ. turn-on energy & switching times vs. collector current, inductive switching

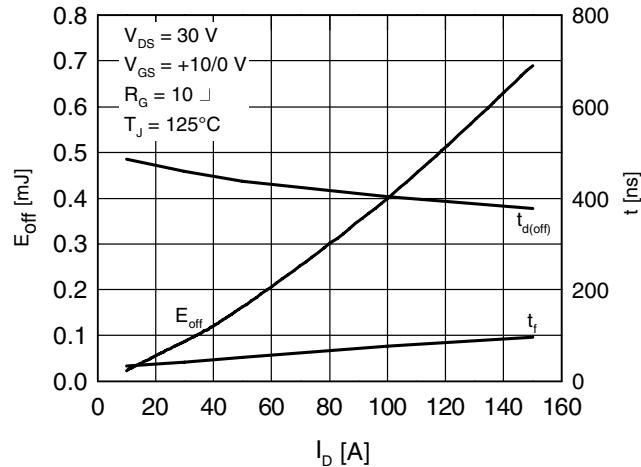


Fig. 10 Typ. turn-off energy & switching times vs. collector current, inductive switching

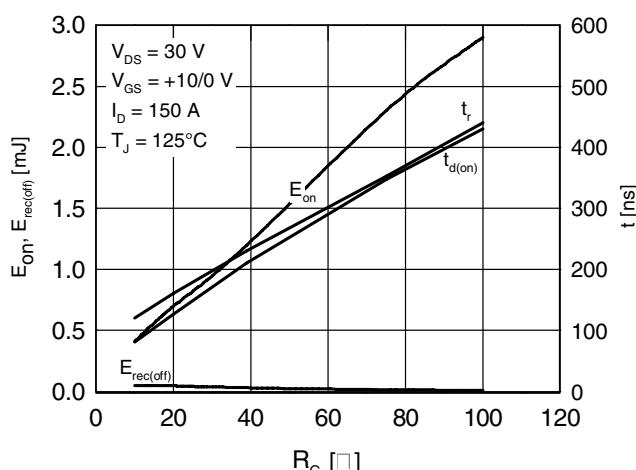


Fig. 11 Typ. turn-on energy & switching times vs. gate resistor, inductive switching

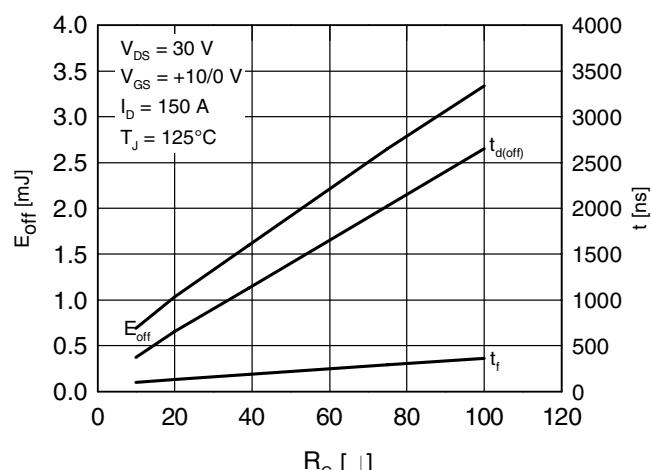


Fig. 12 Typ. turn-off energy & switching times vs. gate resistor, inductive switching

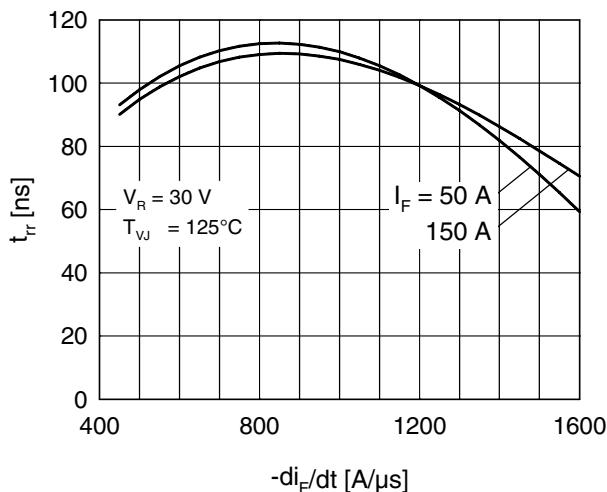


Fig. 13 Reverse recovery time  $t_{rr}$  of the body diode vs.  $di/dt$

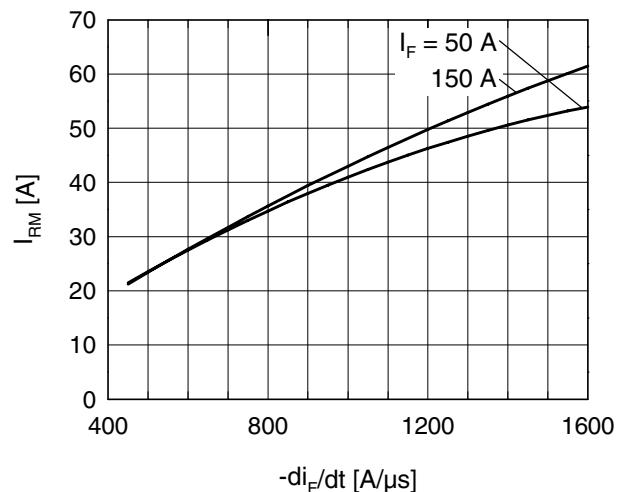


Fig. 14 Reverse recovery current  $I_{RM}$  of the body diode vs.  $di/dt$

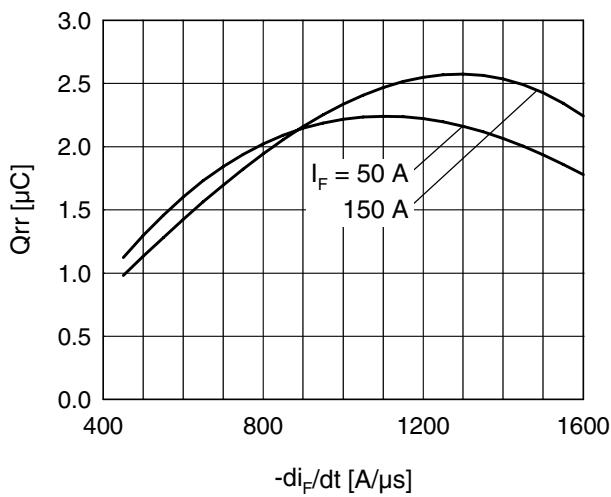


Fig. 15 Reverse recovery charge  $Q_{rr}$  of the body diode vs.  $di/dt$

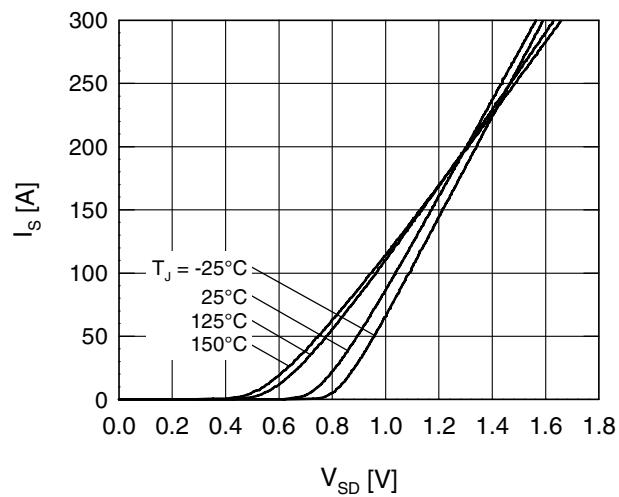


Fig. 16 Source current  $I_S$  vs. source drain voltage  $V_{SD}$  (body diode)

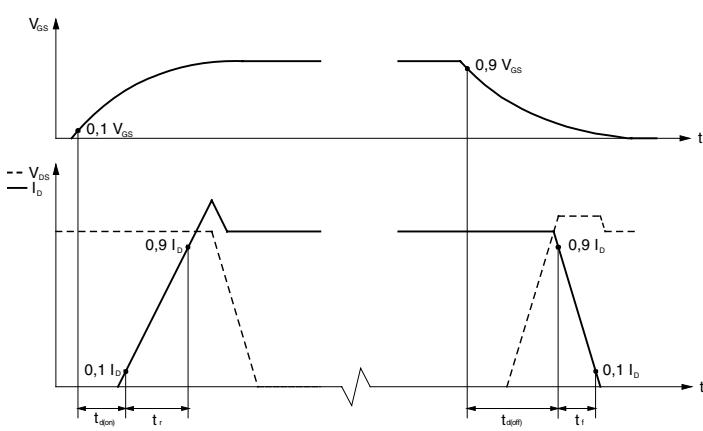


Fig. 17 Definition of switching times

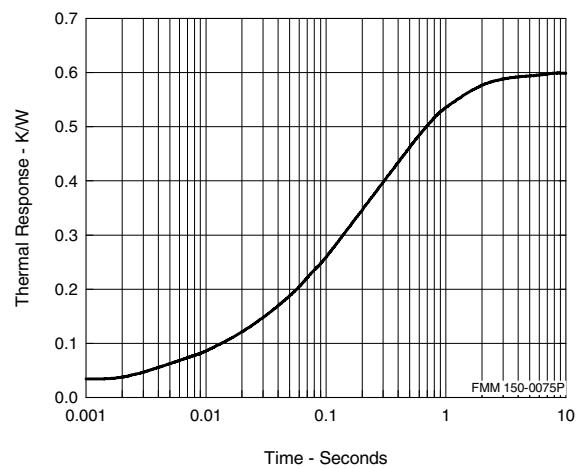


Fig. 18 Therm. impedance junction to case  $Z_{thJC}$